WHAT IS CLAIMED IS:

1. A polishing table for a polishing apparatus configured to polish a substrate, having a support surface configured to support a polishing pad, said polishing pad being adapted to be used for polishing a substrate,

said polishing table comprising:

a stacked body comprising a stack of a porous layer and a non-porous layer, said porous layer including open pores formed in a surface thereof disposed to face a polishing pad; and

a resin-based coating material which adheres to said porous layer at least within said open pores, said resin-based coating material being disposed such that said surface of the porous layer disposed to face the polishing pad is entirely covered by said resin-based coating material.

2. A polishing table according to claim 1, wherein said porous layer comprises a ceramic material.

3. A polishing table according to claims 1 or 2, wherein said non-porous layer includes a flow passage formed therein, which allows a cooling fluid to flow through the polishing table, said flow passage being formed in a position remote from a connection between said porous layer and said non-porous layer.